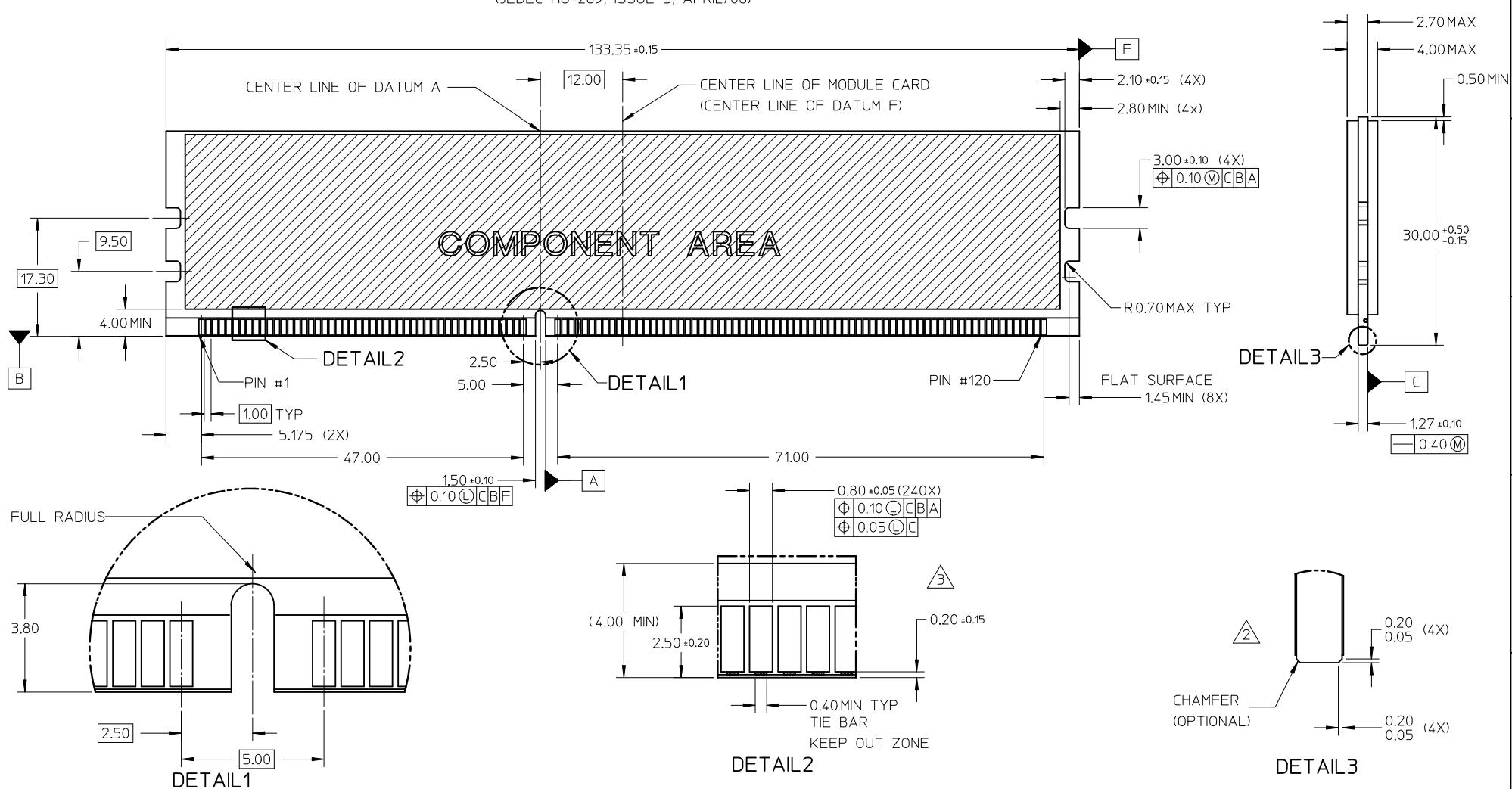


10                    9                    8                    7                    6                    5                    4                    3                    2                    1

## MODULE CARD

DDR3 DUAL IN-LINE MEMORY MODULE FAMILY 1.00MM CONTACT CENTERS  
(JEDEC MO-269, ISSUE B, APRIL /06)



NOTES:

1. RECOMMENDED PLATING FOR CONTACT PADS:

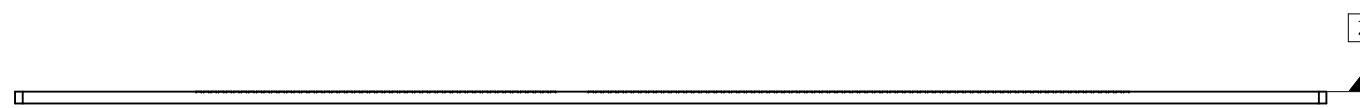
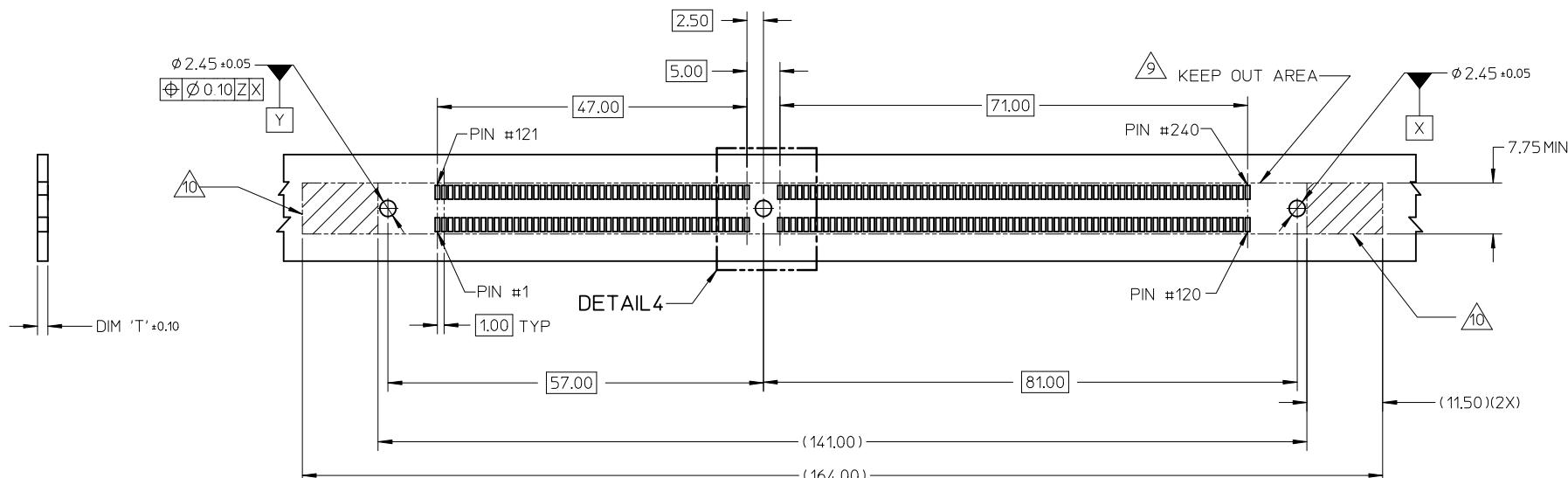
PREFERRED: 0.76 MICROMETERS GOLD PLATING MIN  
OVER 2.00 MICROMETERS NICKEL.

ALTERNATIVE: 0.05-0.75 MICROMETERS GOLD PLATING  
OVER 2.00 MICROMETERS NICKEL MUST USE AN ELECTRONIC  
CONTACT GRADE CORROSIVE BARRIER LUBRICANT.

 **2** CHAMFER IS OPTIONAL AND IS NOT TO HIT THE GOLD PADS

 **3** LEADING EDGE OF GOLD PADS SPECIFIED BY KEEPOUT ZONE  
SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS.

AMD. JEDEC STD. NO. EC NO: S2011-0743		GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
DRMN:CTTEH	2011/02/25			DRAWN BY JAKEEMEW		DATE 2009/04/22	TITLE DDR3 DIMM, 1.00 PITCH 240CKTS, LSP, STD LATCH SMT, VERTICAL, LOWLLCR				
CHKD:CGTAN	2011/04/19			CHECKED BY CCTEH		DATE 2009/05/27					
APPR:SHLENI	2011/04/19			APPROVED BY SHLENI		DATE 2009/05/27	MOLEX MOLEX INCORPORATED				
2	REV A	QUALITY SYMBOLS  = 0  = 0  = 0		mm      INCH		MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-78507-001			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							
6		5		4		3		2		1	
SHEET NO. 3 OF 6											



RECOMMENDED PCB THICKNESS = 1.57mm ~ 3.18mm

RECOMMENDED STENCIL THICKNESS = 150 MICROMETERS

Technical drawing showing a cross-sectional view of a mechanical assembly. The drawing includes several dimensions and tolerance specifications:

- Top left:  $\phi 2.45 \pm 0.05$  (with a note  $\oplus \ominus 0.10$ )
- Top right:  $2.10 \pm 0.03$  (240X) (with a note  $\oplus 0.10$ )
- Bottom right:  $0.70 \pm 0.03$  (240X) (with a note  $\oplus 0.10$ )
- Bottom center:  $2.45$
- Bottom right:  $2.45$

The assembly consists of a central vertical column with horizontal slots. There are three horizontal dashed lines representing different levels. A circular feature is shown at the top level. Dimension lines indicate the height of the central column and the width of the slots. Tolerance values are indicated with  $\pm$  and  $\oplus \ominus$  symbols.

#### DETAIL 4

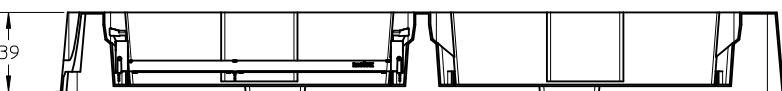
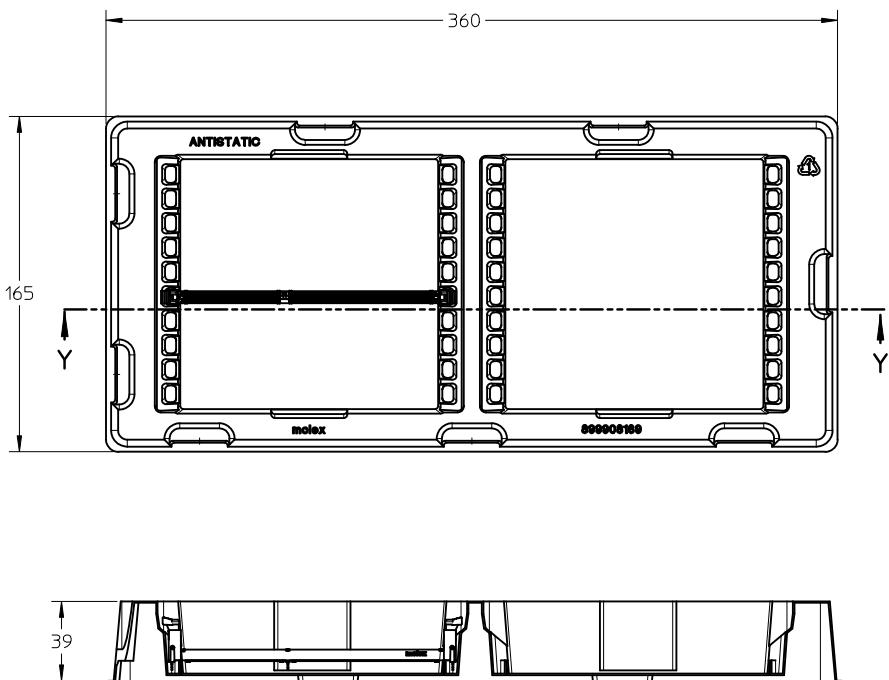
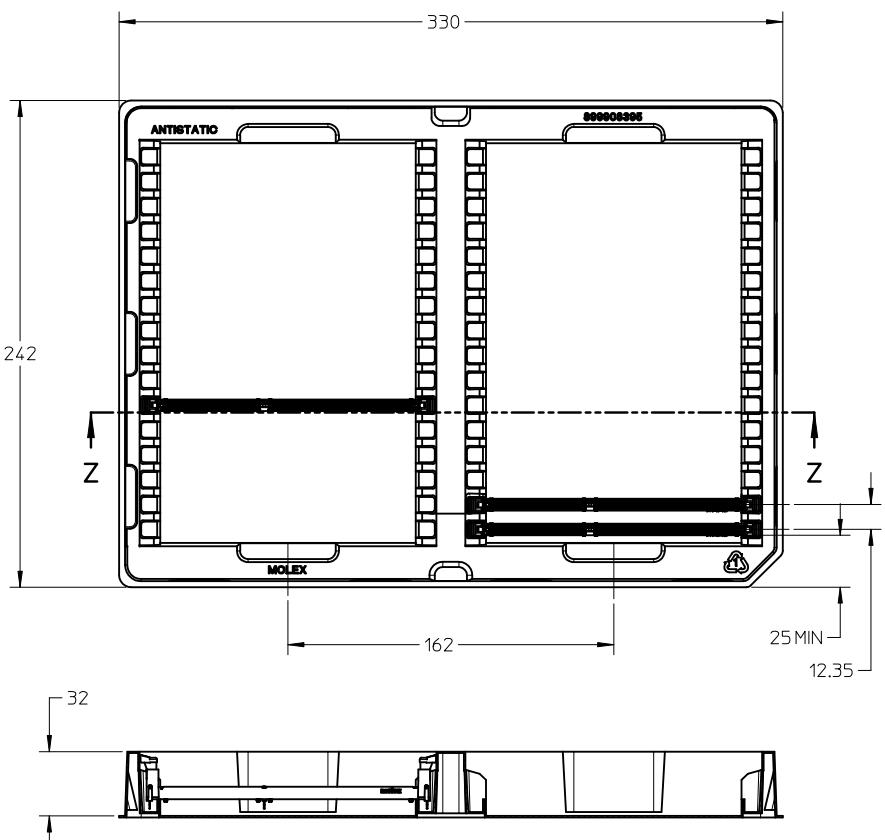
AMD. JEDEC STD. NO.		GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
EC NO: S2011-0743	2011/01/25	DESCRIPTION	mm	INCH	DRAWN BY JAKEEMEW	DATE 2009/04/22	TITLE	DDR3 DIMM, 1.00 PITCH
DRWN:CTEH	2011/04/19	APP'R:SHLENI	4 PLACES	$\pm$ ---	$\pm$ ---	CHECKED BY CCTEH	DATE 2009/05/27	240CKTS, LSP, STD LATCH
CHKD:CTEH	2011/04/19		3 PLACES	$\pm$ ---	$\pm$ ---	APPROVED BY SHLENI	DATE 2009/05/27	SMT, VERTICAL, LOWLLCR
APPR:SHLENI	2011/04/19		2 PLACES	$\pm$ 0.20	$\pm$ ---			molex MOLEX INCORPORATED
			1 PLACE	$\pm$ ---	$\pm$ ---			
			ANGULAR $\pm$ 3 °		MATERIAL NO.	DOCUMENT NO.		SHEET NO.
			DRAFT WHERE APPLICABLE		SEE TABLE	SD-78507-001		4 OF 6
			MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
2		REV						

10 9 8 7 6 5 4 3 2 1

F

F

VIEW FOR PACKAGING TRAY



SECTION Z-Z

TRAY A - NO. OF CAVITY = 2 X 16 = 32PCS

AMD. JEDEC STD. NO. S2011-0743  
DRAWN: CTEH 2011/02/25  
CHKD: GTAN 2011/04/19  
APPR: SHLENI 2011/04/19  
REV. 2

QUALITY SYMBOLS

$\nabla$ <sub>A</sub>=0  
 $\nabla$ <sub>C</sub>=0  
 $\nabla$ <sub>P</sub>=0

DESCRIPTION

GENERAL TOLERANCES (UNLESS SPECIFIED)

mm	INCH
4 PLACES	$\pm$ ---
3 PLACES	$\pm$ ---
2 PLACES	$\pm$ 0.20
1 PLACE	$\pm$ ---
ANGULAR $\pm$ 3°	

DIMENSION STYLE  
MM ONLY

DRAWN BY: NO. OF CAVITY  
TRAY A - NO. OF CAVITY  
CHECKED BY: DATE  
APPROVED BY: DATE  
SHLENI 2009/05/27

SCALE

NTS

2

10

20PCS

1

2

3

4

5

6

7

8

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THIRD ANGLE PROJECTION

DDR3 DIMM, 1.00 PITCH  
240CKTS, LSP, STD LATCH

SMT, VERTICAL, LOWLLCR

MOLEX INCORPORATED

DOCUMENT NO.

SD-78507-001

5 OF 6

tb\_frame\_A3\_P\_AM\_T  
Rev. F 2009/06/18

10 9 8 7 6 5 4 3 2 1

PART NO.	VOLTAGE KEY POS.	DIM 'X'	PLATING OPTION	LATCH COLOR	TRAY TYPE	LUBRICATION
78507-0001	CENTER (1.5V)	3.94	0.76 $\mu$ M (30 $\mu$ INCH) MIN. GOLD ON CONTACT. 2.54 $\mu$ M (100 $\mu$ INCH) MIN. PURE TIN ON SOLDERTAIL. 1.27 $\mu$ M (50 $\mu$ INCH) MIN. NICKEL UNDERPLATE.	BLACK	B	YES
78507-0002					A	
78507-0003				NATURAL (OFF-WHITE)	B	
78507-0004					A	

AMD. JEDEC STD. NO.		GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
EC NO: S2011-0743	2011/02/25	4 PLACES	$\pm$ ---	$\pm$ ---	DRAWN BY JAKEEMEW	DATE 2009/04/22	TITLE DDR3 DIMM, 1.00 PITCH 240CKTS, LSP, STD LATCH SMT, VERTICAL, LOWLLCR			
DRAWN: CTEH	2011/04/19	3 PLACES	$\pm$ ---	$\pm$ ---	CHECKED BY CCTEH	DATE 2009/05/27				
CH'KD: CGTAN	2011/04/19	2 PLACES	$\pm$ 0.20	$\pm$ ---	APPROVED BY SHLENI	DATE 2009/05/27				
APPR: SHLENI		1 PLACE	$\pm$ ---	$\pm$ ---	MOLEX MOLEX INCORPORATED					
		ANGULAR	$\pm$ 3 °							
REV 2		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-78507-001	SHEET NO. 6 OF 6	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
		SIZE A3								

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